



Product Change Notification

Change Notification #: 118879-00
Change Title: Intel® Server Chassis H2224XXLR3,
PCN 118879-00, Product Design,
Gasket implementation on 2.5" Tool Less
Carrier (TLC)
Date of Publication: January 24, 2022

Key Characteristics of the Change:

Product Design

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material*	February 08, 2022
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* Intel appreciates the customer's desire to receive the latest revision of products. However, Intel manages inventory on a first in first out (FIFO) basis at the MM# level. Subsequently, customer requests for a specific revision of material (below the MM#) will not be supported by Intel.

Description of Change to the Customer:

The Intel SKUs listed in the products affected table will have the following change. A gasket has been added on each side of the 2.5" tool less carrier (TLC), improving the flow of electricity.

Tool Less Carrier (TLC) 2.5"



Customer Impact of Change and Recommended Action:

Intel anticipates no impact to customers. Please contact your local Intel Field Sales Representative if you have any further questions about these changes.

Products Affected/Intel Ordering Codes:

Marketing Name	Product Code	MM#	Pre Change TA	Post Change TA
Intel® Server Chassis H2224XXLR3	H2224XXLR3	948907	J57870-011	J57870-012

PCN Revision History:

Date of Revision:

January 24, 2022

Revision Number:

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Reason:

Originally Published PCN



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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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